

B.L. Berman, S.D. Bloom, and S. Datz, *Phys. Rev. Lett.* **42** (1979) p. 1148.  
 13. J.U. Andersen and E. Laegsgaard, *Phys. Rev. Lett.* **44** (1980) p. 1079.  
 14. J.A. Martin, M. Nastasi, J.R. Tesmer, and C.J. Maggiore, *Appl. Phys. Lett.* **52** (1988) p. 2177.  
 15. D. Schroyen, M. Bruggeman, I. Dézsi, and G. Langouche, *Nucl. Instrum. Methods B* **15** (1986) p. 341.  
 16. D. Sigurd, R.W. Bower, W.F. van der Weg, and J.W. Mayer, *Appl. Phys.* **45** (1974) p. 1740.  
 17. L.C. Feldman, J.W. Mayer, and S.T. Picraux, *Materials Analysis by Ion Channeling* (Academic Press, New York, 1982).  
 18. J.U. Andersen, O. Andreason, J.A. Davies, and E. Uggerhøj, *Radiat. Eff.* **7** (1971) p. 25.

19. B. Domeij and K. Björkqvist, *Phys. Lett.* **14** (1965) p. 127.  
 20. H. Hofsäass, S. Winter, S.G. Jahn, U. Wahl, and E. Recknagel, *Nucl. Instrum. Methods B* **63** (1992) p. 83.  
 21. M. Lindroos, H. Haas, J. De Wachter, H. Pattyn, and G. Langouche, to be published.  
 22. M.F. Wu, A. Vantomme, G. Langouche, K. Maex, H. Vanderstraeten, and Y. Bruynseraede, *Appl. Phys. Lett.* **57** (1990) p. 1973.  
 23. N.R. Parikh, G.S. Sandhu, N. Yu, W.K. Chu, T.E. Jackman, J.-M. Baribeau, and D.C. Houghton, *Thin Solid Films* **163** (1988) p. 455.  
 24. C.K. Pan, D.C. Zheng, T.G. Finstad, W.K. Chu, V.S. Speriosu, M-A. Nicolet, and

J.H. Barrett, *Phys. Rev B* **31** (1985) p. 1270.  
 25. S.T. Picraux, W.K. Chu, W.R. Allen, and J.A. Ellison, *Nucl. Instrum. Methods B* **15** (1986) p. 306.  
 26. W.K. Chu, J.A. Ellison, S.T. Picraux, R.M. Biefeld, and G.C. Osbourn, *Phys. Rev. Lett.* **52** (1984) p. 125.  
 27. S.T. Picraux, R.M. Biefeld, W.R. Allen, W.K. Chu, and J.A. Ellison, *Phys. Rev B* **38** (1988) p. 11086.  
 28. W.K. Chu, W.R. Allen, S.T. Picraux, and J.A. Ellison, *Phys. Rev B* **42** (1990) p. 5923.  
 29. L.C. Feldman and J.W. Mayer, *Fundamentals of Surface and Thin Film Analysis* (North Holland, 1986). □

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